Hyperfast Rectifier, 30 A FRED Pt®

TO-247AC 2L

Common cathode
2, Base

1 Cathode   3 Anode

LINKS TO ADDITIONAL RESOURCES

3D Models

FEATURES

- Hyperfast recovery time
- Low forward voltage drop
- 175 °C operating junction temperature
- Low leakage current
- Single diode device
- Designed and qualified according to JEDEC®-JESD 47
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912

Pb-free
RoHS COMPLIANT
HALOGEN FREE Available

DESCRIPTION / APPLICATIONS

State of the art hyperfast recovery rectifiers designed with optimized performance of forward voltage drop, hyperfast recovery time and soft recovery.

The planar structure and the platinum doped life time control guarantee the best overall performance, ruggedness and reliability characteristics.

These devices are intended for use in PFC boost stage in the AC/DC section of SMPS, inverters or as freewheeling diodes.

Their extremely optimized stored charge and low recovery current minimize the switching losses and reduce over dissipation in the switching element and snubbers.

MECHANICAL DATA

Case: TO-247AC 2L
Molding compound meets UL 94 V-0 flammability rating

Terminals: matte tin plated leads, solderable per J-STD-002

PRIMARY CHARACTERISTICS

$I_{F(AV)}$	30 A
V_R	600 V
V_F at I_F	1.34 V
t_{rr} typ.	See Recovery table
T_J max.	175 °C
Package	TO-247AC 2L
Circuit configuration	Single

ABSOLUTE MAXIMUM RATINGS

PARAMETER	SYMBOL	TEST CONDITIONS	VALUES	UNITS
Peak repetitive reverse voltage	V_{RRM}		600	V
Average rectified forward current	$I_{F(AV)}$	$T_C = 116$ °C	30	A
Non-repetitive peak surge current	I_{FSM}	$T_J = 25$ °C, $t_p = 10$ ms	300	
Operating junction and storage temperatures	T_J, T_{Stg}		-65 to +175	°C

ELECTRICAL SPECIFICATIONS ($T_J = 25$ °C unless otherwise specified)

PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Breakdown voltage, blocking voltage	V_{BR}, V_R	$I_R = 100$ µA	600	-	-	V
Forward voltage	V_F	$I_F = 30$ A	-	2.0	2.6	V
		$I_F = 30$ A, $T_J = 150$ °C	-	1.34	1.75	
Reverse leakage current	I_R	$V_R = V_R$ rated	-	0.3	50	µA
		$T_J = 150$ °C, $V_R = V_R$ rated	-	60	500	
Junction capacitance	C_T	$V_R = 600$ V	-	33	-	pF
Series inductance	L_S	Measured lead to lead 5 mm from package body	-	3.5	-	nH

DYNAMIC RECOVERY CHARACTERISTICS (T_J = 25 °C unless otherwise specified)

PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNITS
Reverse recovery time	t_{rr}	I_F = 1.0 A, dI_F/dt = 50 A/µs, V_R = 30 V		-	28	35	ns
		T_J = 25 °C	I_F = 30 A dI_F/dt = 200 A/µs V_R = 200 V	-	31	-	
		T_J = 125 °C		-	77	-	
Peak recovery current	I_{RRM}	T_J = 25 °C		-	3.5	-	A
		T_J = 125 °C		-	7.7	-	
Reverse recovery charge	Q_{rr}	T_J = 25 °C		-	65	-	nC
		T_J = 125 °C		-	345	-	

THERMAL - MECHANICAL SPECIFICATIONS

| PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Maximum junction and storage temperature range	T_J, T_{Stg}		-65	-	175	°C
Thermal resistance, junction to case per leg	R_{thJC}		-	0.5	0.9	°C/W
Thermal resistance, junction to ambient per leg	R_{thJA}	Typical socket mount	-	-	40	
Thermal resistance, case to heatsink	R_{thCS}	Mounting surface, flat, smooth and greased	-	0.4	-	
Weight			-	6.0	-	g
Mounting torque			6.0 (5.0)	-	12 (10)	kgf · cm (lbf · in)
Marking device		Case style TO-247AC 2L	30EPH06			
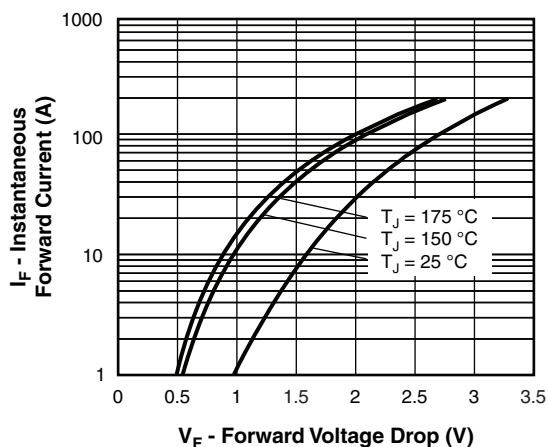
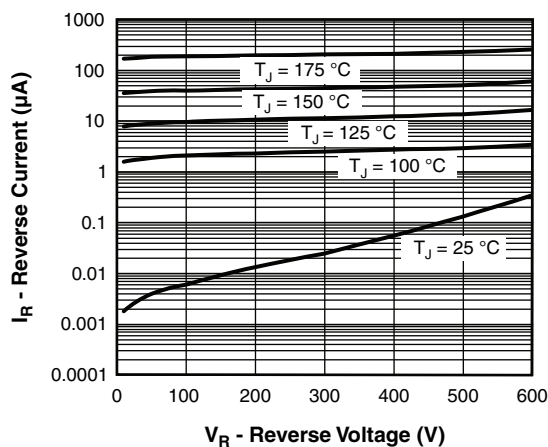Fig. 1 - Typical Forward Voltage Drop Characteristics

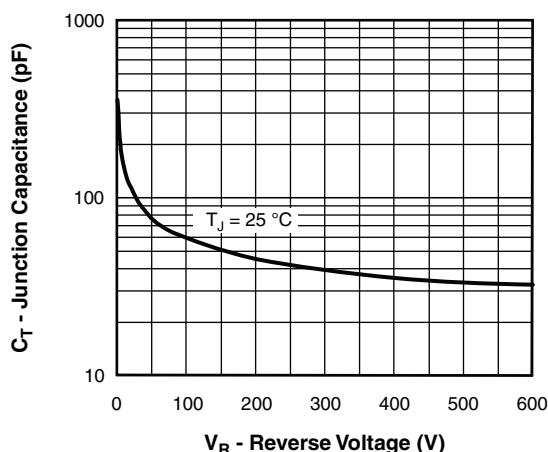Fig. 2 - Typical Values of Reverse Current vs. Reverse Voltage

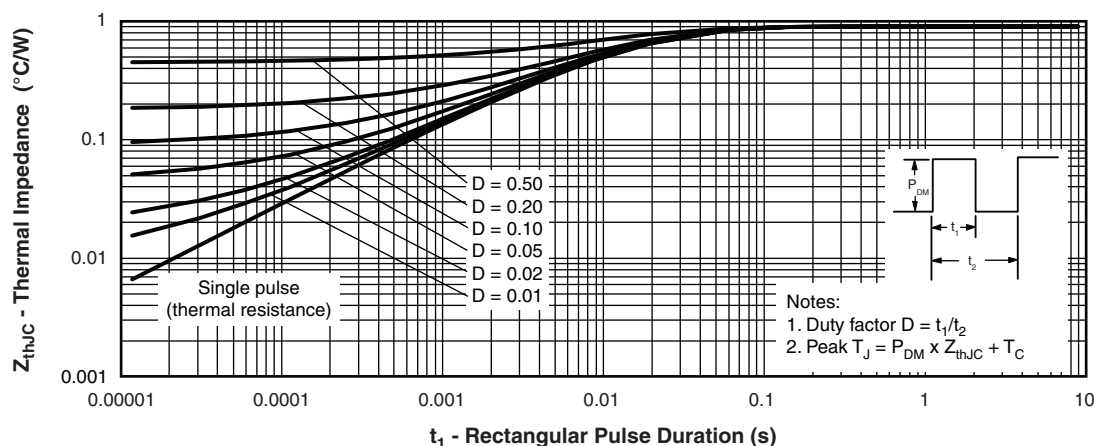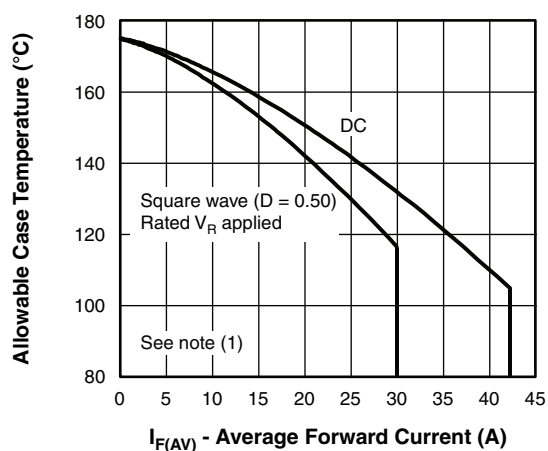Fig. 3 - Typical Junction Capacitance vs. Reverse Voltage

Fig. 4 - Maximum Thermal Impedance Z_{thJC} Characteristics

Fig. 5 - Maximum Allowable Case Temperature vs. Average Forward Current
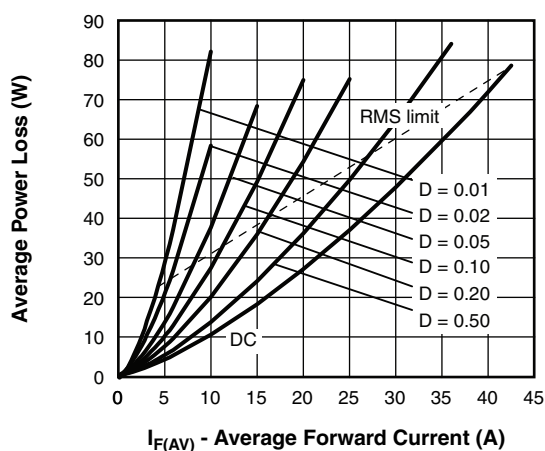

Fig. 6 - Forward Power Loss Characteristics

Note

(1) Formula used: $T_C = T_J - (Pd + Pd_{REV}) \times R_{thJC}$;
Pd = forward power loss = $I_{F(AV)} \times V_{FM}$ at ($I_{F(AV)}$/D) (see fig. 6);
Pd_{REV} = inverse power loss = $V_{R1} \times I_R (1 - D)$; I_R at V_{R1} = rated V_R
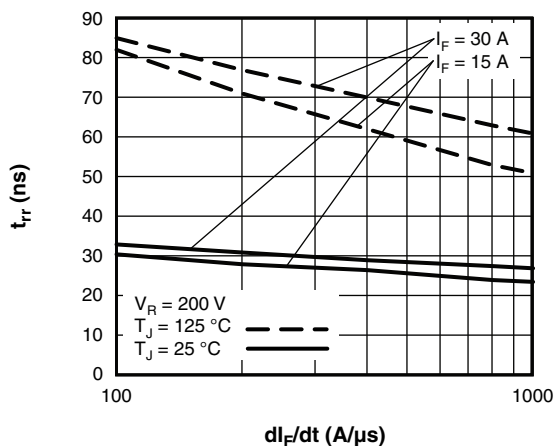
Fig. 7 - Typical Reverse Recovery Time vs. dI$_F$/dt
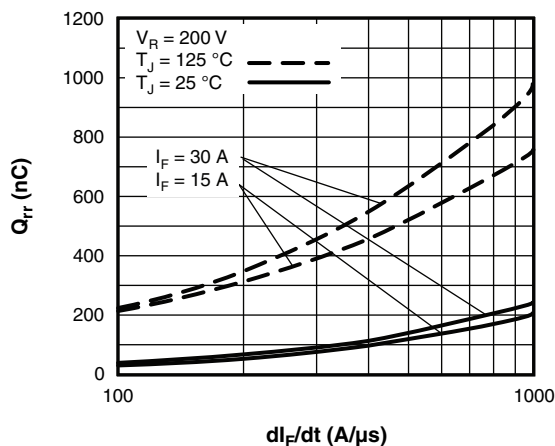
Fig. 8 - Typical Stored Charge vs. dI$_F$/dt
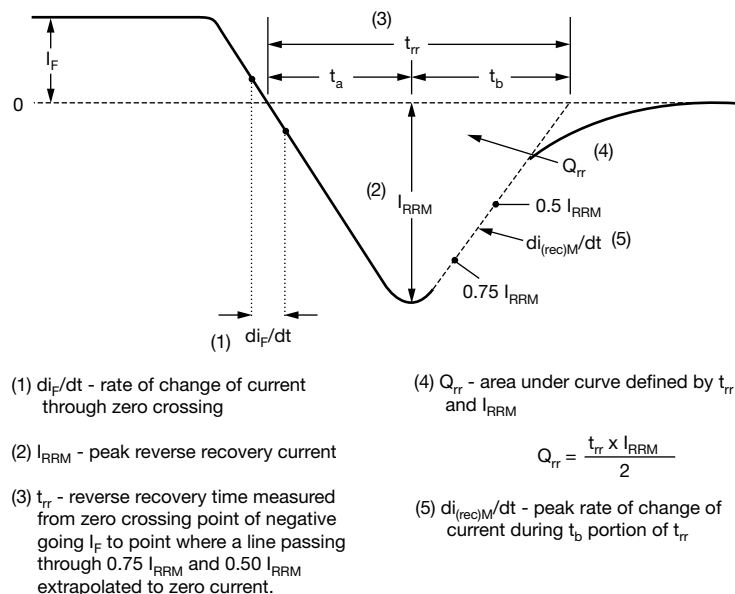
Fig. 9 - Reverse Recovery Waveform and Definitions

(1) di$_F$/dt - rate of change of current through zero crossing

(2) I$_{RRM}$ - peak reverse recovery current

(3) t$_{rr}$ - reverse recovery time measured from zero crossing point of negative going I$_F$ to point where a line passing through 0.75 I$_{RRM}$ and 0.50 I$_{RRM}$ extrapolated to zero current.

(4) Q$_{rr}$ - area under curve defined by t$_{rr}$ and I$_{RRM}$

$$Q_{rr} = \frac{t_{rr} \times I_{RRM}}{2}$$

(5) di$_{(rec)M}$/dt - peak rate of change of current during t$_b$ portion of t$_{rr}$

ORDERING INFORMATION TABLE

Device code	VS-	30	E	P	H	06	-N3
	①	②	③	④	⑤	⑥	⑦

1	-	Vishay Semiconductors product
2	-	Current rating (30 = 30 A)
3	-	Circuit configuration: E = single diode
4	-	Package: P = TO-247AC
5	-	H = hyperfast recovery
6	-	Voltage rating (06 = 600 V)
7	-	Environmental digit: -N3 = halogen-free, RoHS-compliant, and totally lead (Pb)-free

| ORDERING INFORMATION (Example)			
PREFERRED P/N	**QUANTITY PER T/R**	**MINIMUM ORDER QUANTITY**	**PACKAGING DESCRIPTION**
VS-30EPH06-N3	25	500	Antistatic plastic tube

LINKS TO RELATED DOCUMENTS	
Dimensions	www.vishay.com/doc?96144
Part marking information	www.vishay.com/doc?95648
SPICE model	www.vishay.com/doc?96573

TO-247AC 2L

DIMENSIONS in millimeters and inches

Section C - C, D - D

View B

View A - A
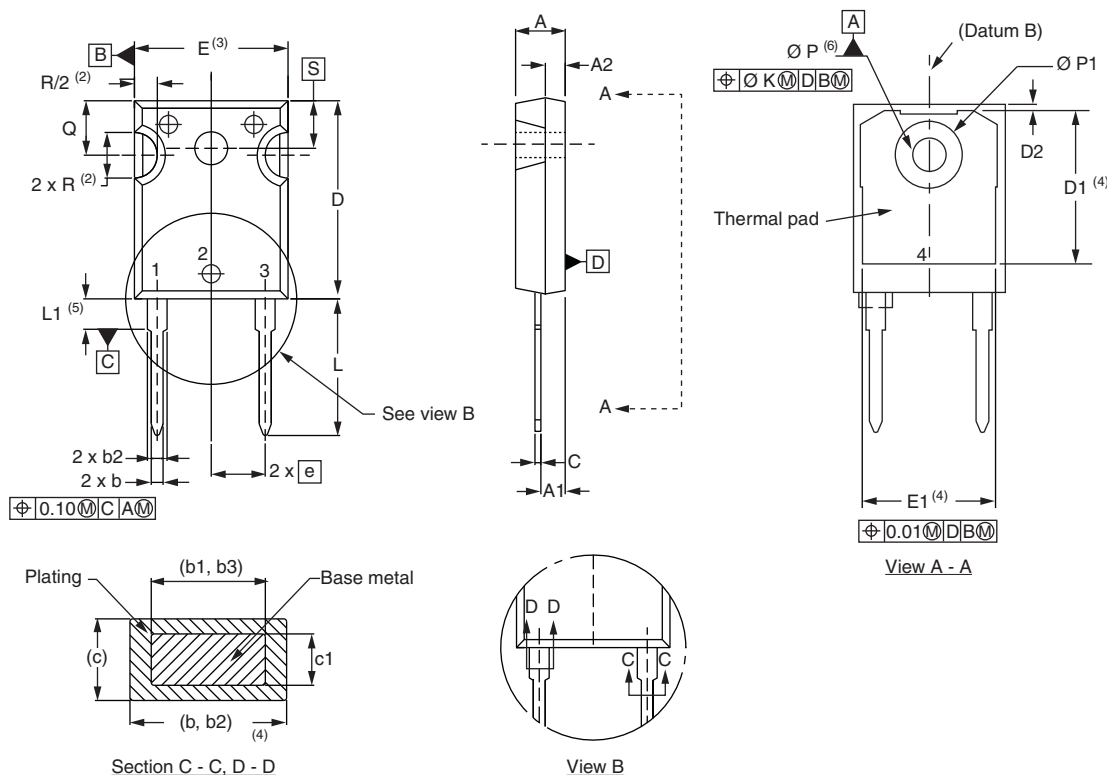
SYMBOL	MILLIMETERS		INCHES		NOTES
	MIN.	MAX.	MIN.	MAX.	
A	4.65	5.31	0.183	0.209	
A1	2.21	2.59	0.087	0.102	
A2	1.17	1.37	0.046	0.054	
b	0.99	1.40	0.039	0.055	
b1	0.99	1.35	0.039	0.053	
b2	1.65	2.39	0.065	0.094	
b3	1.65	2.34	0.065	0.092	
c	0.38	0.89	0.015	0.035	
c1	0.38	0.84	0.015	0.033	
D	19.71	20.70	0.776	0.815	3
D1	13.08	-	0.515	-	4
D2	0.51	1.35	0.020	0.053	

SYMBOL	MILLIMETERS		INCHES		NOTES
	MIN.	MAX.	MIN.	MAX.	
E	15.29	15.87	0.602	0.625	3
E1	13.46	-	0.53	-	
e	5.46 BSC		0.215 BSC		
Ø K	0.254		0.010		
L	14.20	16.10	0.559	0.634	
L1	3.71	4.29	0.146	0.169	
Ø P	3.56	3.66	0.14	0.144	
Ø P1	-	7.39	-	0.291	
Q	5.31	5.69	0.209	0.224	
R	4.52	5.49	0.178	0.216	
S	5.51 BSC		0.217 BSC		

Notes

[1] Dimensioning and tolerancing per ASME Y14.5M-1994

[2] Contour of slot optional

[3] Dimension D and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outermost extremes of the plastic body

[4] Thermal pad contour optional with dimensions D1 and E1

[5] Lead finish uncontrolled in L1

[6] Ø P to have a maximum draft angle of 1.5 to the top of the part with a maximum hole diameter of 3.91 mm (0.154")

[7] Outline conforms to JEDEC® outline TO-247 with exception of dimension Q

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